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IN THE U.S. PATENT AND TRADEMARK OFFICE

plicant(s): Iver E. ANDERSON, et al

For : Pb-FREE Sn-Ag-Cu TERNARY EUTECTIC SOLDER

Serial No. : 08/094 854

Group : 3205

Filed

: July 20, 1993

Examiner: Knapp

August 11, 1994

Atty. Docket

No.: ISU Case 340

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GROUP 3200

The Commissioner of Patents and Trademarks Washington, D. C. 20231

RESPONSE TO FIRST OFFICE ACTION

Sir:

In response to the Office Action mailed March 16, 1994, Applicants amend as follows:

IN THE SPECIFICATION

Page 1, between the title and Field of the Invention, insert the following paragraph:

---/The United States Government has rights in this invention pursuant to Contract No. W-7405-ENG-82 between the U.S. Department of Energy and Iowa State University, Ames, Iowa, which contract grants to Iowa State University Research Foundation, Inc. the right to apply for this patent./--.

IN THE CLAIMS

Please cancel Claims 5, 7, 10, 13 and 17 without prejudice. Please amend the following claims:

1. (Amended) A Pb-free <u>electrical conductor</u> solder consisting essentially of about 3.5 to about 7.7 weight % Ag, about 1.0 to about 4.0 weight % Cu and the balance essentially Sn wherein Sn is present in an amount of at least about 89 weight % Sn.

Claim 6, line 8; replace "relative to" with ---not exceeding

/ 15°C above---.

Claim 11, line 2; delete "essentially".

Claim 12, line 9; replace "relative to" with ---not exceeding

15°C above---.

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